



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

## Product Specification

▶ Domestic	Part Number	AO6402
▶ Overseas	Part Number	AO6402
▶ Equivalent	Part Number	AO6402

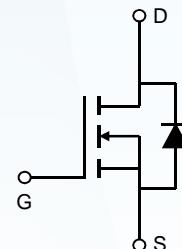


EV is the abbreviation of name EVVO

## 30V N-Channel MOSFET

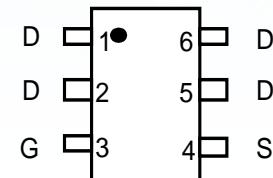
## General Description

The AO6402A uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge. This device is suitable for use as a load switch or in PWM applications. The source leads are separated to allow a Kelvin connection to the source, which may be used to bypass the source inductance.



## Features

- $V_{DS}$  (V) = 30V
- $I_D$  = 7.5A ( $V_{GS}$  = 10V)
- $R_{DS(ON)}$  < 24mΩ ( $V_{GS}$  = 10V)
- $R_{DS(ON)}$  < 35mΩ ( $V_{GS}$  = 4.5V)



SOT23-6

Absolute Maximum Ratings  $T_A=25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Maximum		Units
Drain-Source Voltage	$V_{DS}$	30		V
Gate-Source Voltage	$V_{GS}$	$\pm 20$		V
Continuous Drain Current <sup>A,F</sup>	$I_D$	7.5		A
$T_A=70^\circ\text{C}$		6.0		
Pulsed Drain Current <sup>B</sup>	$I_{DM}$	64		
Power Dissipation	$P_D$	2.0		W
$T_A=70^\circ\text{C}$		1.28		
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150		°C

## Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient <sup>A</sup>	$R_{\theta JA}$	48	62.5	°C/W
Steady-State		74	110	°C/W
Maximum Junction-to-Lead <sup>C</sup>	$R_{\theta JL}$	54	68	°C/W

## 30V N-Channel MOSFET

Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	30			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$			1	$\mu\text{A}$
		$T_J=55^\circ\text{C}$			5	
$I_{\text{GSS}}$	Gate-Body leakage current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$			100	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.5	2.1	2.6	V
$I_{\text{D(ON)}}$	On state drain current	$V_{GS}=10\text{V}, V_{DS}=5\text{V}$	64			A
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}, I_D=7.5\text{A}$		17.3	24	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=5.6\text{A}$		25	35	$\text{m}\Omega$
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=7.5\text{A}$		20		S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$		0.75	1	V
$I_S$	Maximum Body-Diode Continuous Current				2.5	A
<b>DYNAMIC PARAMETERS</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=15\text{V}, f=1\text{MHz}$		373	448	pF
$C_{\text{oss}}$	Output Capacitance			67		pF
$C_{\text{rss}}$	Reverse Transfer Capacitance			41		pF
$R_g$	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$		2	2.8	$\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, I_D=7.5\text{A}$		7.2	11	nC
$Q_g(4.5\text{V})$	Total Gate Charge			3.5	5	nC
$Q_{\text{gs}}$	Gate Source Charge			1.3		nC
$Q_{\text{gd}}$	Gate Drain Charge			1.7		nC
$t_{\text{D(on)}}$	Turn-On DelayTime	$V_{GS}=10\text{V}, V_{DS}=15\text{V}, R_L=2\Omega, R_{\text{GEN}}=3\Omega$		4.5	6.5	ns
$t_r$	Turn-On Rise Time			2.7	4.5	ns
$t_{\text{D(off)}}$	Turn-Off DelayTime			14.9	23	ns
$t_f$	Turn-Off Fall Time			2.9	5.5	ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=7.5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		10.5	12.6	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=7.5\text{A}, dI/dt=100\text{A}/\mu\text{s}$		4.5	5.4	nC

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

B: Repetitive rating, pulse width limited by junction temperature.

C. The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using <300  $\mu\text{s}$  pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$ . The SOA curve provides a single pulse rating.

F. The current rating is based on the  $t \leq 10\text{s}$  thermal resistance rating.

## 30V N-Channel MOSFET

### TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

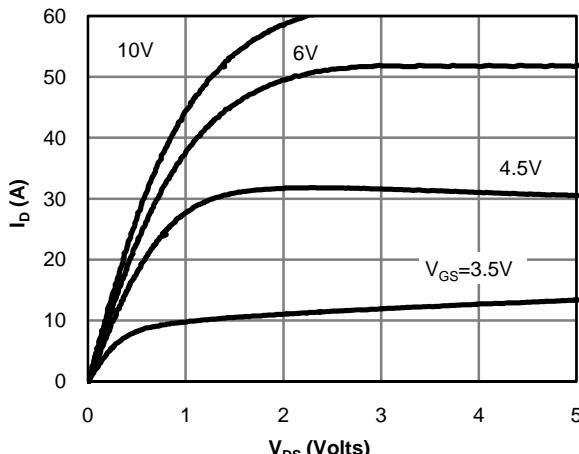


Fig 1: On-Region Characteristics

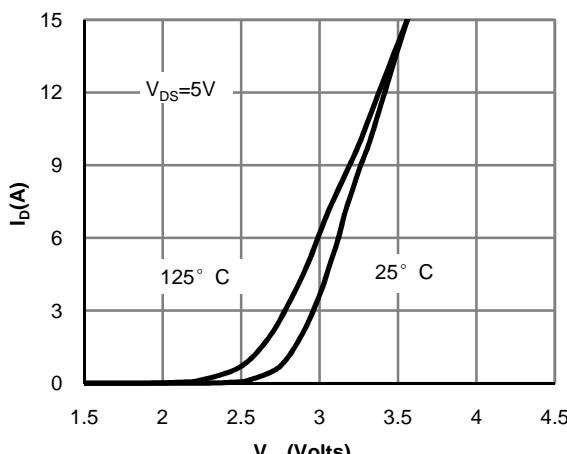


Fig 2: Transfer Characteristics

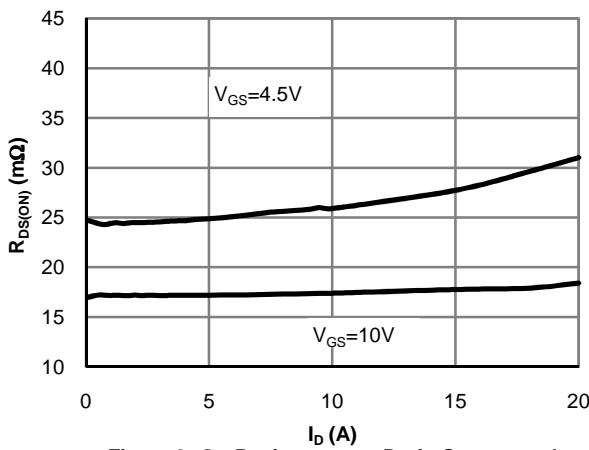


Fig 3: On-Resistance vs. Drain Current and Gate Voltage

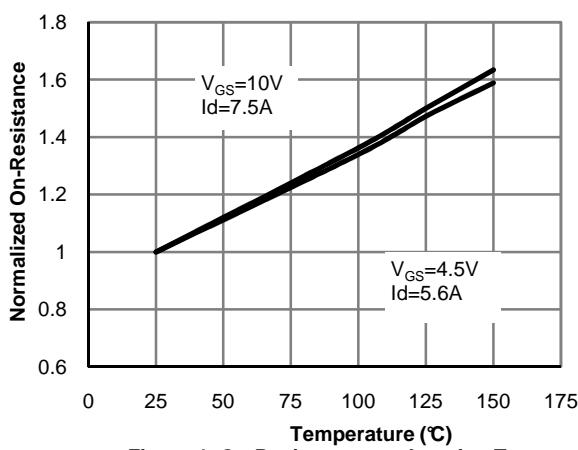


Fig 4: On-Resistance vs. Junction Temperature

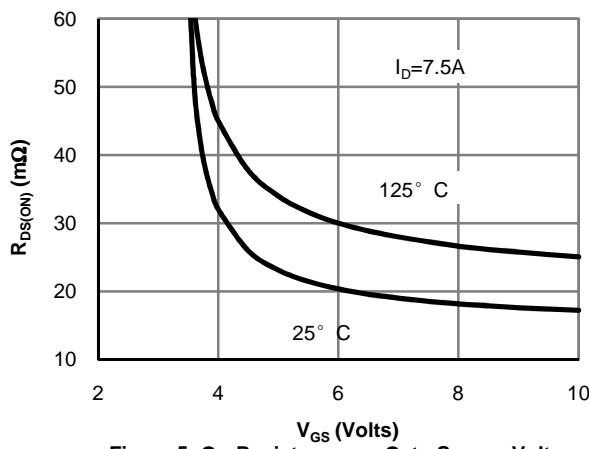


Fig 5: On-Resistance vs. Gate-Source Voltage

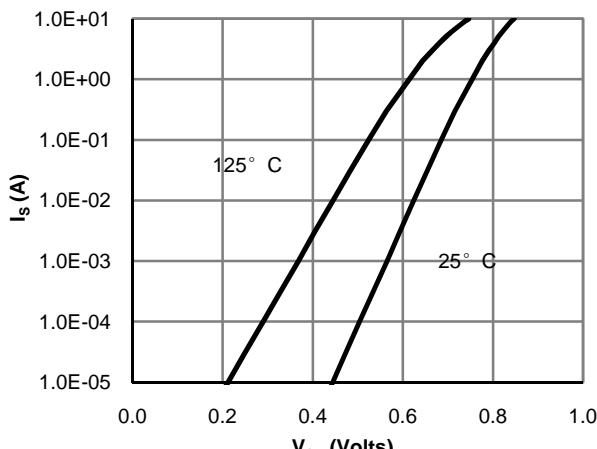
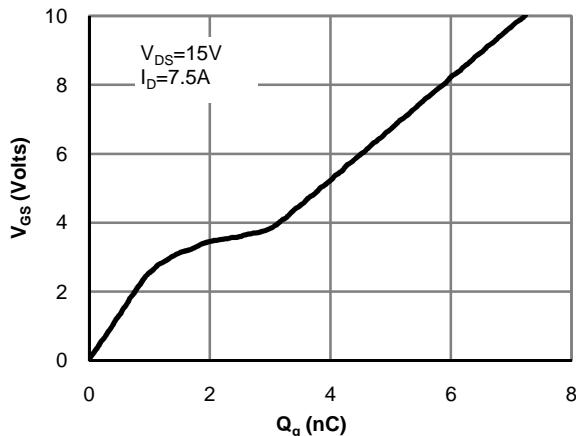
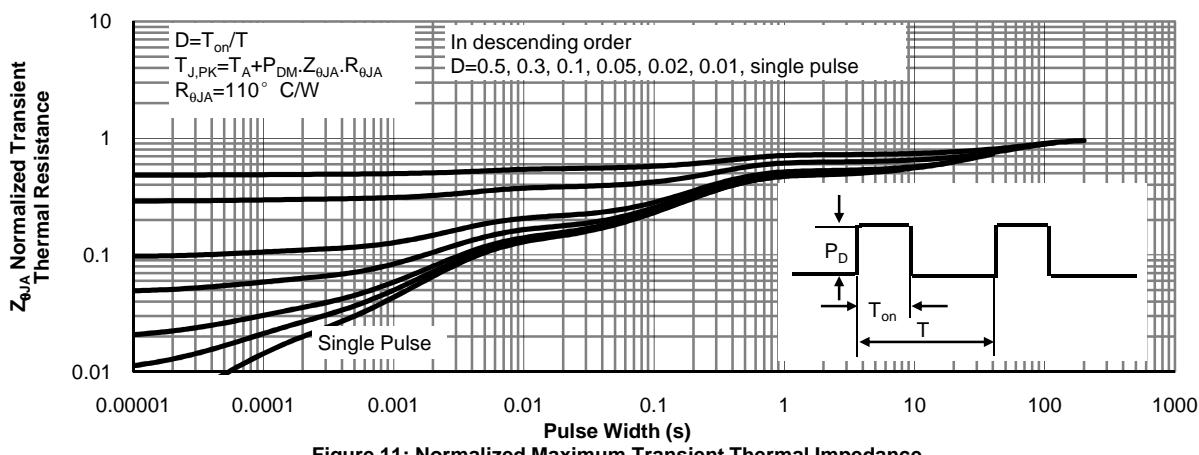
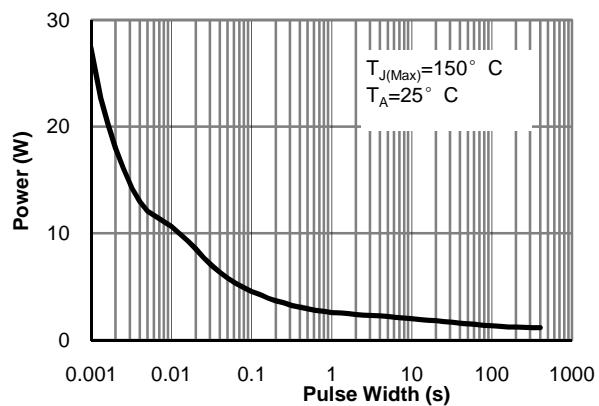
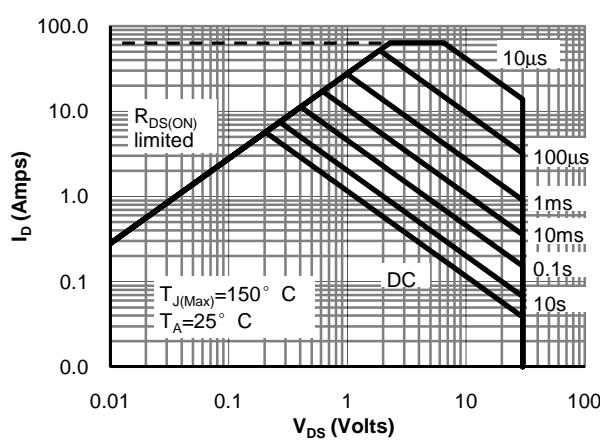
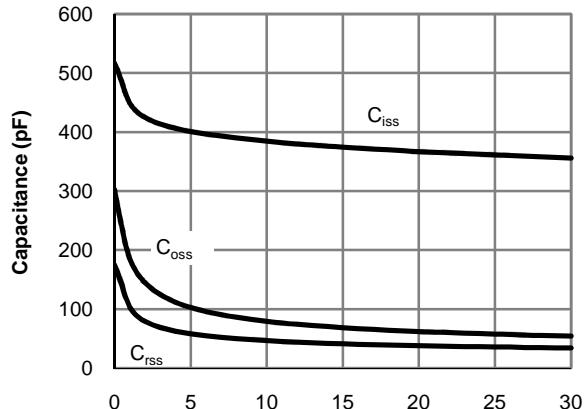


Fig 6: Body-Diode Characteristics

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

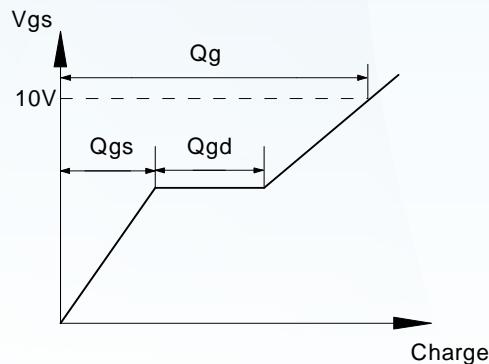
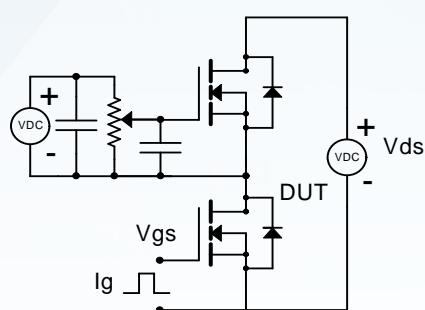


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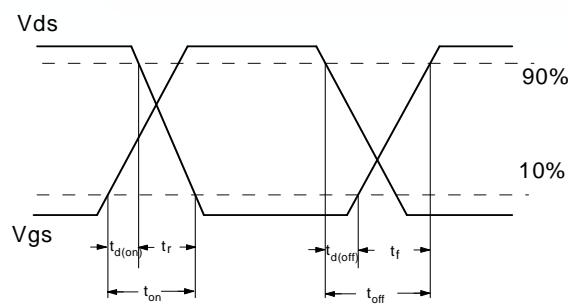
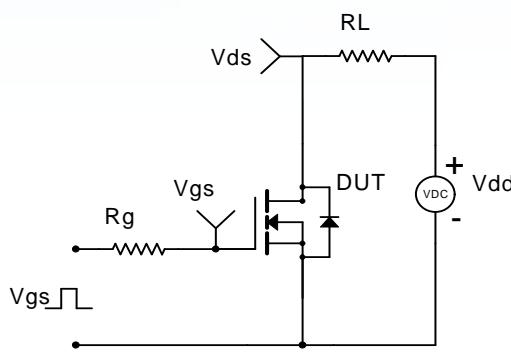


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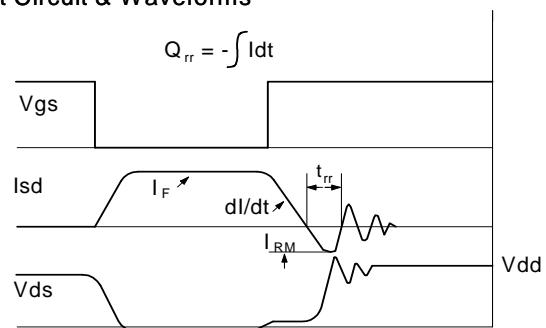
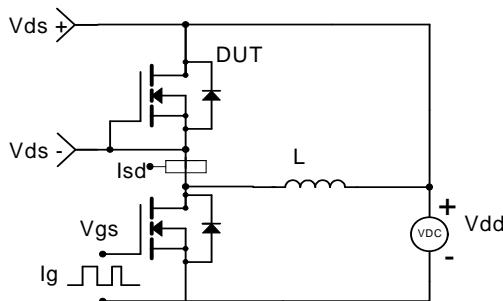
Gate Charge Test Circuit & Waveform

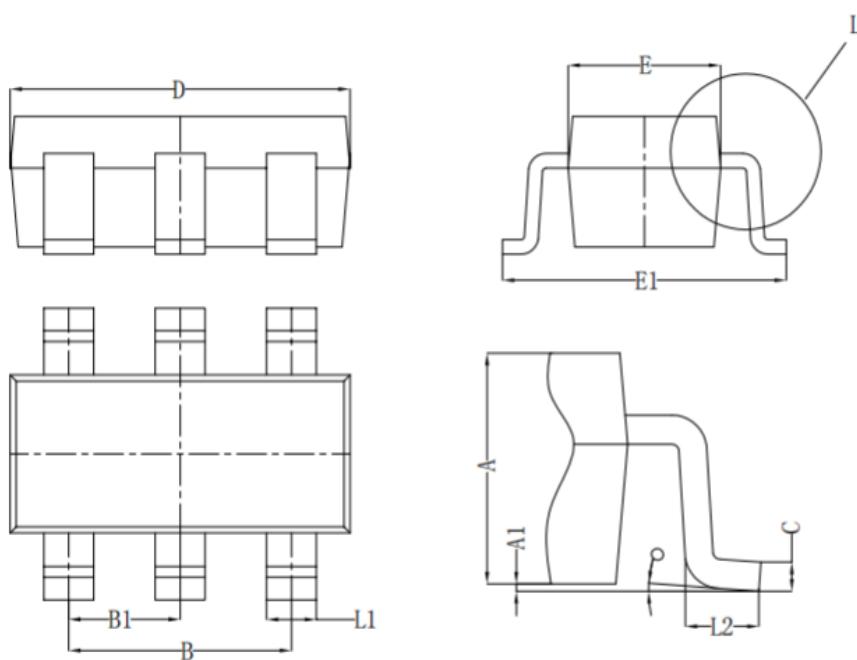


Resistive Switching Test Circuit & Waveforms

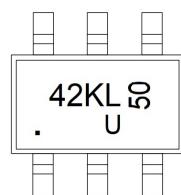


Diode Recovery Test Circuit & Waveforms



**30V N-Channel MOSFET****SOT23- 6 PACKAGE OUTLINE DIMENSIONS**

Symbol	Dim in mm		
	Min	Nor	Max
A	1.050	1.100	1.150
A1	0.000	0.050	0.100
L1	0.300	0.400	0.500
C	0.100	0.150	0.200
D	2.820	2.920	3.020
E	1.500	1.600	1.700
E1	2.650	2.800	2.950
B	1.800	1.900	2.000
B1	0.950 TYP		
L2	0.300	0.450	0.600
o	0°	4°	8°

**30V N-Channel MOSFET****Marking****Ordering information**

Order code	Package	Baseqty	Deliverymode
AO6402A	SOT23-6	3000	Tape and reel

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